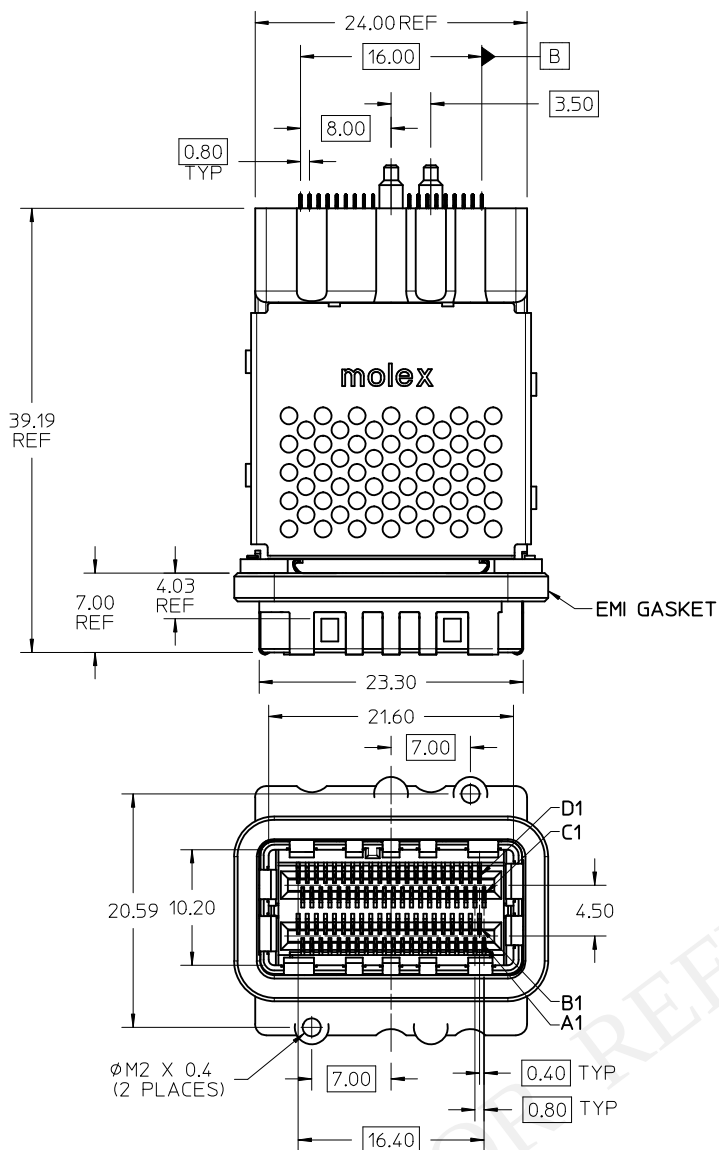
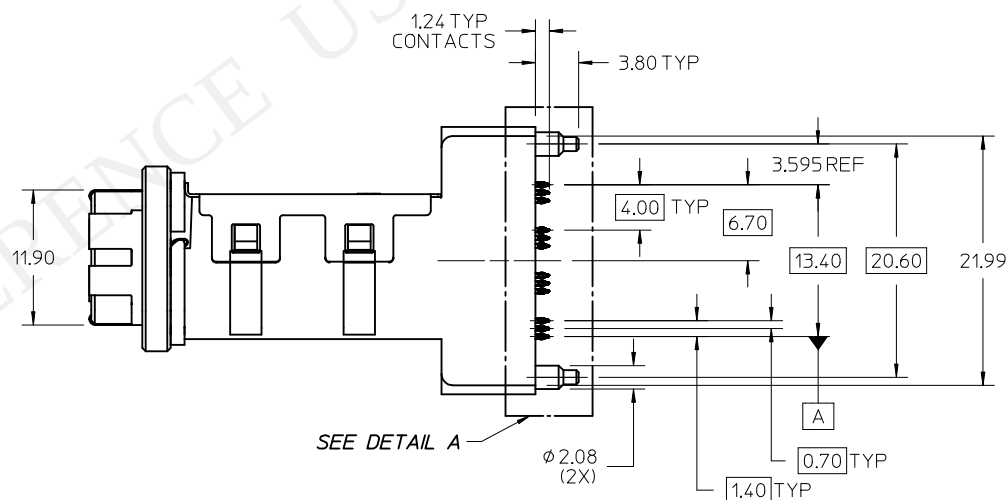
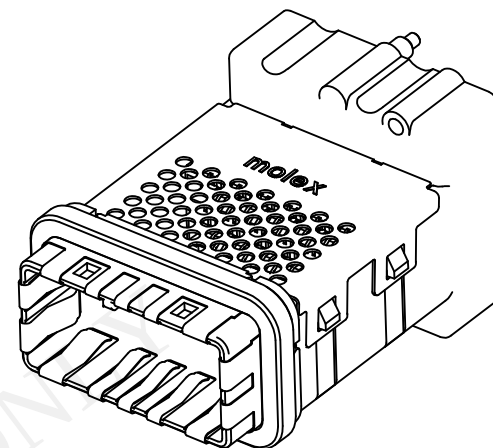
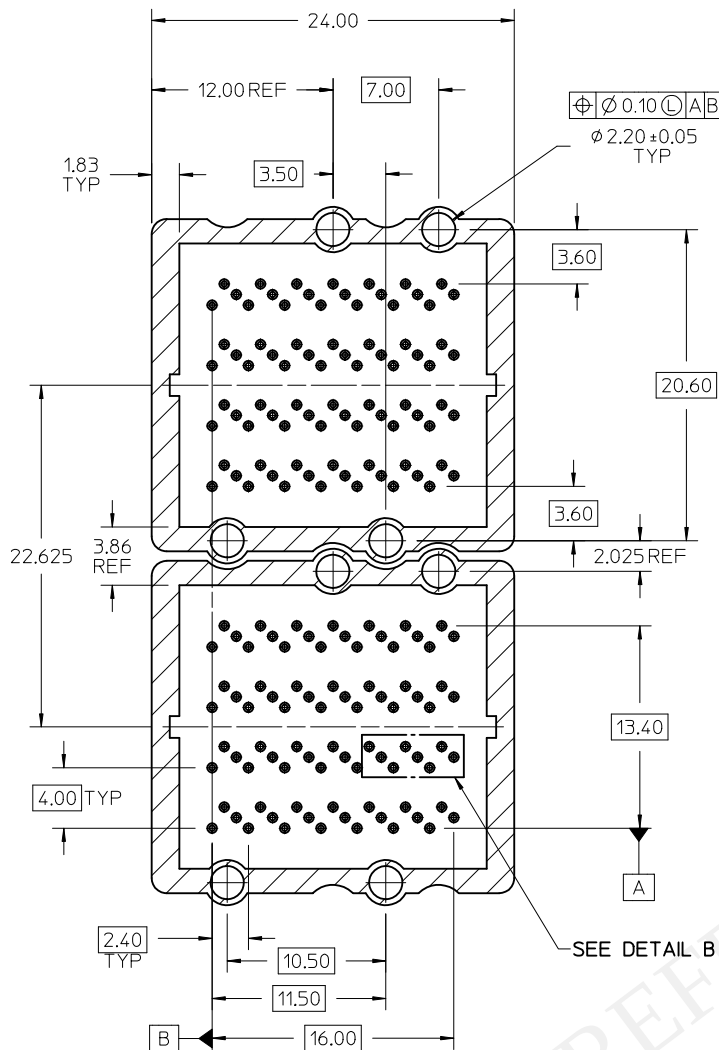


DETAIL A
SCALE 4:1

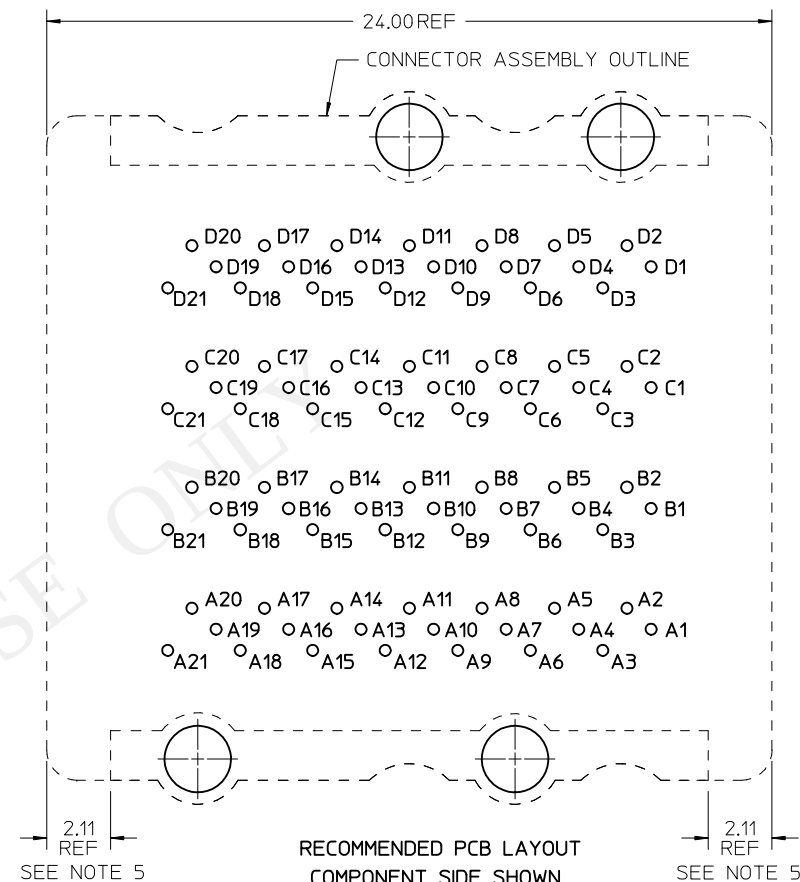


- NOTES:
- MATERIALS:
CONNECTOR HOUSING: HIGH TEMPERATURE THERMOPLASTIC
GLASS-FILLED, UL 94V-0
EMI HOUSING: NICKEL PLATED DIE CAST ALLOY
COVER: STAINLESS STEEL ALLOY
EMI GASKET: CONDUCTIVE POLYMER
TERMINALS: COPPER ALLOY
 - PLATING:
769970022 - CONTACT AREA: 0.764mm MIN. GOLD OVER 2.544mm MIN. NICKEL
TIN TAIL AREA: 0.764mm - 1.524mm TIN OVER 2.544mm MIN NICKEL
 - THIS CONNECTOR IS DESIGNED TO MATE WITH MOLEX IPASS CABLES.
 - PACKAGING SPECIFICATION: TRAY PACK PER PK-76997-001.
 - MOUNTING HARDWARE REQUIRED: M2x0.4 CAP SCREWS (4), SEE SHEET 3
 - PRODUCT SPECIFICATION: PS-76997-001.
 - APPLICATION SPECIFICATION: AS-76997-001.

RELEASE TO 'A' EC NO: UCP2013-3343 DRAWING PRATT 2012/10/17 CHKD: MBANAKIS 2013/02/07 APPR: MBANAKIS 2013/02/13	DESCRIPTION	QUALITY SYMBOLS F=0 E=0 F=0	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 3:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
					mm	INCH	DRAWN BY GPRATT	DATE 2013/02/07	TITLE VERTICAL CXP ASSEMBLY HIGH SPEED CHANNEL 0.8MM I/O			
			4 PLACES		± ---	± ---	CHECKED BY MBANAKIS	DATE 2013/02/07	molex DOCUMENT NO. SD-76997-242 SHEET NO. 1 OF 3			
			3 PLACES		± ---	± ---	APPROVED BY MBANAKIS				DATE 2013/02/13	
			2 PLACES		± 0.25	± ---	MATERIAL NO. SEE CHART					
			1 PLACE		± ---	± ---						
			0 PLACE		± ---	± ---						
					ANGULAR ±1/2°							
					DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							
							SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

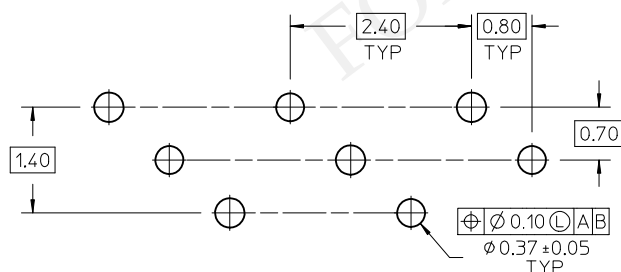


RECOMMENDED PCB LAYOUT
COMPONENT SIDE SHOWN
MULTIPLE APPLICATION SHOWN
ON MINIMUM PITCH
PCB THICKNESS: 1.57mm MIN.



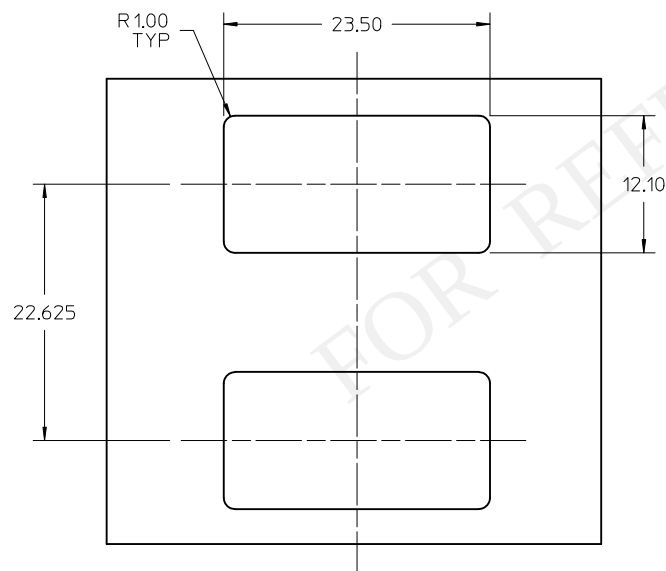
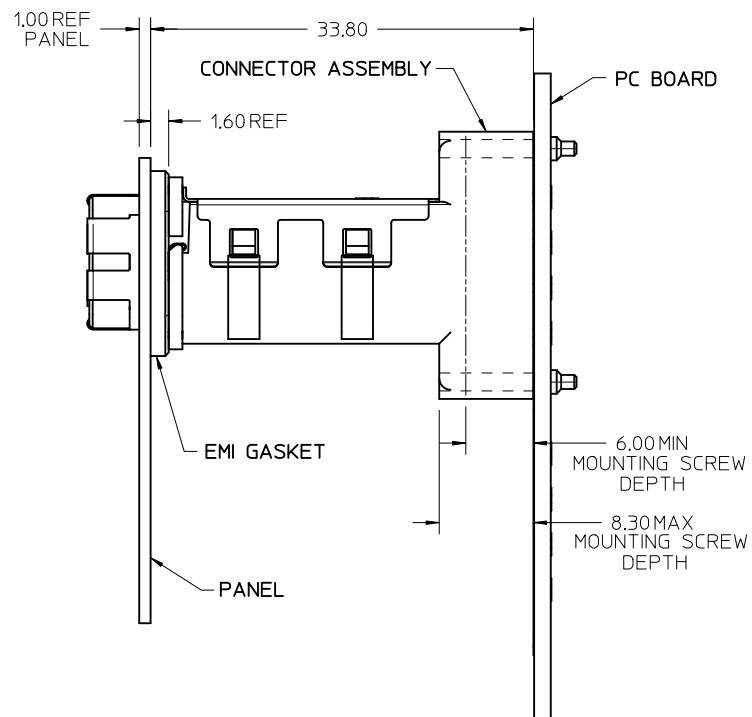
NOTES:

- CROSS-HATCHED AREA TO BE CONDUCTIVE ON THE PCB.
- CROSS-HATCHED AREA MUST BE INCORPORATED IN THE FLAT ROCK PRESS-FIT TOOLING.
- REFER TO THE PLATING DETAIL OF THE COMPLIANT PIN HOLES IN THE APPLICATION SPEC AS-76997-002 FOR THE DRILL SIZE AND ANNULAR RING FOR THE 0.37 $\varnothing$ FINISHED HOLE.
- DIE CAST RELEIVED 1.5MM IN THIS AREA.

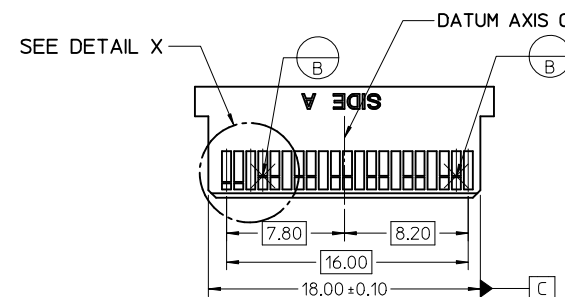
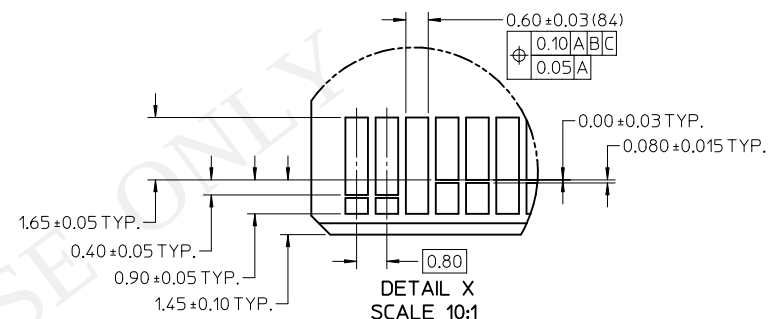
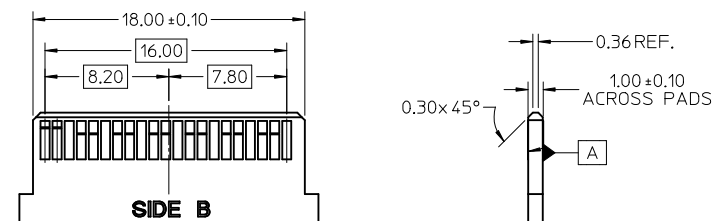


DETAIL B
(TYPICAL ROW LAYOUT)

SEE SHEET 1 EC NO: UCP2013-3343 2012/10/17 DRWG:GPRATT CHKD:MBANAKIS 2013/02/07 APP:MBANAKIS 2013/02/13	DESCRIPTION	QUALITY SYMBOLS 	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION VERTICAL CXP ASSEMBLY HIGH SPEED CHANNEL 0.8MM I/O molex SD-76997-242	SHEET NO. 2 OF 3
					DRAWN BY GPRATT	DATE 2013/02/07	TITLE			
					CHECKED BY MBANAKIS	DATE 2013/02/07				
					APPROVED BY MBANAKIS	DATE 2013/02/13				
					MATERIAL NO.		DOCUMENT NO.			
					SEE SHEET 1					
					SIZE C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



I/O PANEL CUT-OUT



- NOTES:
- 0.03 MINIMUM KEEP OUT FOR SOLDER MASK AROUND ALL PADS
 - DATUM B TARGETS ARE DEFINED BY THE RESPECTIVE PAD CENTER LINES AND THE LEADING EDGE OF THE TARGET PADS

RECOMMENDED PADDLE CARD LAYOUT

SEE SHEET 1	EC NO: UCP2013-3343			REV	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 3:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
	2012/10/17						mm		INCH		DRAWN BY		DATE		TITLE VERTICAL CXP ASSEMBLY HIGH SPEED CHANNEL 0.8MM I/O molex		
	2013/02/07						4 PLACES ± ---		± ---		GPRATT		2013/02/07				
	2013/02/13						3 PLACES ± ---		± ---		CHECKED BY		DATE				
							2 PLACES ± 0.25		± ---		MBANAKIS		2013/02/07				
							1 PLACE ± ---		± ---		APPROVED BY		DATE				
							0 PLACE ± ---		± ---		MBANAKIS		2013/02/13				
							ANGULAR ± 1/2°				MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
							DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SEE SHEET 1		SD-76997-242		3 OF 3		
											SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				